

5GHz - 9GHz Packaged Bessel Filter

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TGB2010-SM

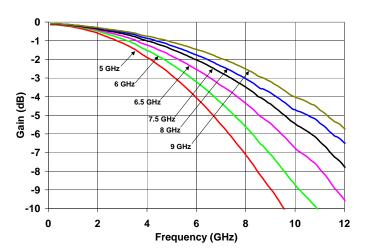
Key Features and Performance

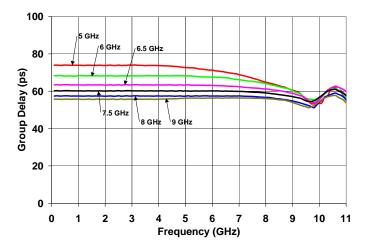
- 5, 6, 6.5, 7.5, 8, 9 GHz and Thru Filters
- <±2.0ps Group Delay to F_o
- Typical >15dB Return Loss to F_o
- Filter Bandwidth ± 0.5 GHz
- Package Dimensions: 2 x 2 x 0.90 mm

Primary Applications

- High-Speed Optical Networks
- Filter Networks

Preliminary Measured Performance





Product Description

The TGB2010-SM Bessel Filter has low inband return loss, low group delay variation, and a smaller package footprint than competing filters. Insertion loss and group delay for each filter matches an ideal 3rd order Bessel filter and is matched to 50 Ohms eliminating the need for additional components for multiple reflection management.

A range of 5 to 9 GHz cutoff frequencies in 1GHz steps are available. The TGB2010-SM series package size is 2mm x 2mm allowing integration on tightly packed circuit boards.

Evaluation Boards are available.

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TABLE I MAXIMUM RATINGS

Symbol	Parameter	Value	Notes
P _{IN}	Input Continuous Wave Power		<u>1</u> /
	in-band	17 dBm	
	out-of-band	11 dBm	
T _{ASSY}	Assembly Temperature	260 °C	
T _{STG}	Storage Temperature	-65 to 150 ⁰ C	

1/ These ratings represent the maximum operable values for this device

TABLE IITGB2010-SM RF CHARACTERIZATION TABLE(T_A = 25°C, Nominal)

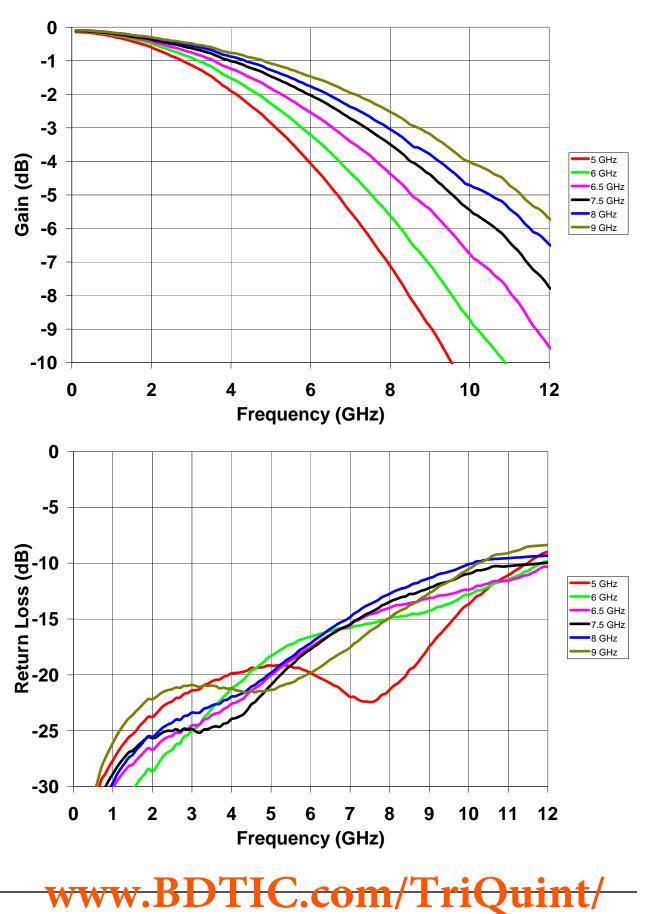
Symbol	Parameter	Test Conditions	Typical	Units	Notes
Fo	3dB Bandwidth (GHz)	F = 5, 6, 6.5, 7.5, 8, 9	±0.5	GHz	
Т _g	Group Delay Variation Within 3dB Bandwidth	F = 5 - 9	±2.0	pS	
RL _{5GHz}	Return Loss	F = DC - 5 GHz	15	dB	
RL _{6GHz}	Return Loss	F = DC - 6 GHz	15	dB	
RL _{6.5GHz}	Return Loss	F = DC - 6.5 GHz	15	dB	
RL _{7.5GHz}	Return Loss	F = DC - 7.5 GHz	15	dB	
RL _{8GHz}	Return Loss	F = DC - 7 GHz	15	dB	
RL _{9GHz}	Return Loss	F = DC - 7 GHz	15	dB	

Note: Table II Lists the RF Characteristics of typical devices as determined by fixtured measurements.

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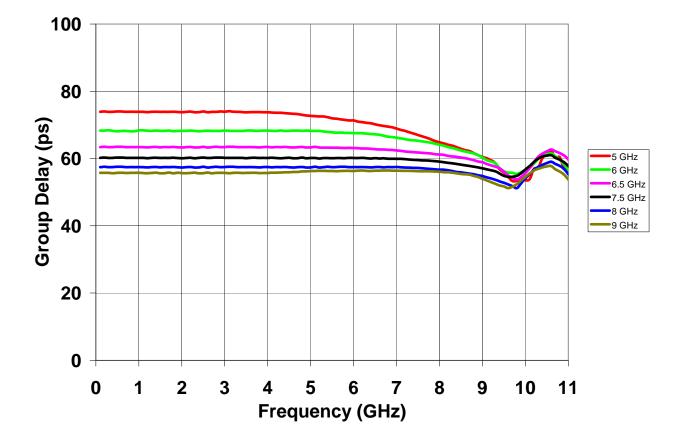


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Measured Fixture Performance



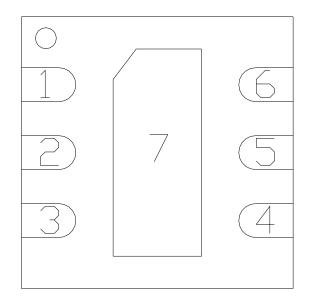


Measured Fixture Performance

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Package Pinout

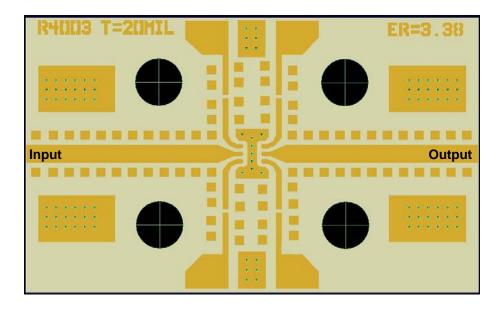


Top View

Pin	Signal
1	NC
2	Input
3	NC
4	NC
5	Output
6	NC
7 (Paddle)	Ground



Evaluation Board

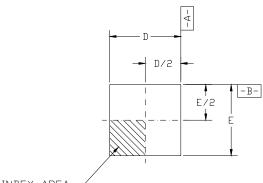


Note: No external components required.

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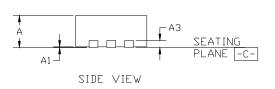


Packaged Dimensional Drawing TGB2010-SM

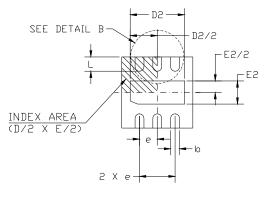


INDEX AREA

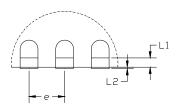




Symbol	MIN	NDM	MAX	UNITS
A	0.80	0.90	1.00	mm
A1	0.00	0.02	0.05	mm
A3		0.20 ref		mm
L1			0.15	mm
L2			0.13	mm
b	0.18	0.25	0.30	mm
D	1.85	2.00	2.15	mm
E	1.85	2.00	2.15	mm
D2	1.30		1.75	mm
E2	0.50		0.80	mm
L	0.30	0.40	0.50	mm
e	0.45	0.50	0.55	mm



BOTTOM VIEW



DETAIL B

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Assembly of TGB2010-SM Surface Mount Package onto a Circuit Board

Solders designated Pb-free such as SnAgCu have reflow temperatures which are higher than those required for Sn/Pb. Typical soldering temperatures are 20 to 30 degrees higher. The molding compound used in this package can withstand 260°C peak temperatures. In addition, the molding compound is free of flame retardants defined by some regulations as hazardous.

1. Clean the circuit board or module with Acetone. Rinse with alcohol and DI water. Allow the circuit to fully dry.

2. To improve the RF performance, we recommend attaching the paddle on the bottom of the package using Pb free solder.

- 3. Apply Pb free solder to each circuit board pad and to the backside contact for the package.
- 4. Reflow using manufacturer recommended oven and solder profiles.
- 5. Clean the assembly with alcohol.

Ordering Information

PACKAGE PART NUMBER DESIGNATIONS

Part No	Package Style	Cutoff Frequency
TGB2010-00-SM	MLF/QFN	Thru
TGB2010-50-SM	MLF/QFN	$5.0\pm0.5~\text{GHz}$
TGB2010-60-SM	MLF/QFN	$6.0\pm0.5~\text{GHz}$
TGB2010-65-SM	MLF/QFN	$6.5\pm0.5~ ext{GHz}$
TGB2010-75-SM	MLF/QFN	$7.5\pm0.5~\text{GHz}$
TGB2010-80-SM	MLF/QFN	$8.0\pm0.5~\text{GHz}$
TGB2010-90-SM	MLF/QFN	$9.0\pm0.5~\text{GHz}$

Note: Package marked with 2 digit center frequency and manufacturing week only.

